



TARGET THICKNESS: 0.078"
NUMBER OF LAYERS: 12

MULTILAYER PCB CONSTRUCTION SHEET

If there are max thickness requirements beyond +/- .10% overall - non-standard construction should be ordered and notes added.

12 Layer StackUp (0.078") L12-078-1oz1oz		Thickness (inches)
Layer 1	1 oz foil plated to approximate* thickness 0.0024"	0.0024
Prepreg	Bonding ply (1x1080, 1x2116) Average Dielectric Constant 4.5	0.0064
Layer 2	1 oz foil thickness	0.0014
Core	Laminate Core Average Dielectric Constant 4.5	0.005
Layer 3	1 oz foil thickness	0.0014
Prepreg	Bonding ply (1x1080, 1x2116) Average Dielectric Constant 4.5	0.0064
Layer 4	1 oz foil thickness	0.0014
Core	Laminate Core Average Dielectric Constant 4.5	0.005
Layer 5	1 oz foil thickness	0.0014
Prepreg	Bonding ply (1x1080, 1x2116) Average Dielectric Constant 4.5	0.0064
Layer 6	1 oz foil thickness	0.0014
Core	Laminate Core Average Dielectric Constant 4.5	0.005
Layer 7	1 oz foil thickness	0.0014
Prepreg	Bonding ply (1x1080, 1x2116) Average Dielectric Constant 4.5	0.0064
Layer 8	1 oz foil thickness	0.0014
Core	Laminate Core Average Dielectric Constant 4.5	0.005
Layer 9	1 oz foil thickness	0.0014
Prepreg	Bonding ply (1x1080, 1x2116) Average Dielectric Constant 4.5	0.0064
Layer 10	1 oz foil thickness	0.0014
Core	Laminate Core Average Dielectric Constant 4.5	0.005
Layer 11	1 oz foil thickness	0.0014
Prepreg	Bonding ply (1x1080, 1x2116) Average Dielectric Constant 4.5	0.0064
Layer 12	1 oz foil plated to approximate* thickness 0.0024"	0.0024
"Thickness does not include soldermask or surface finish"		0.0798

NOTES: